

APPLICATIONS

- Induction Heating
- A.C. Motor Drives
- Snubber Diode
- Welding
- High Frequency Rectification
- UPS

KEY PARAMETERS

V_{RRM}	1600V
$I_{F(AV)}$	205A
I_{FSM}	3000A
Q_r	35μC
t_{rr}	3.2μs

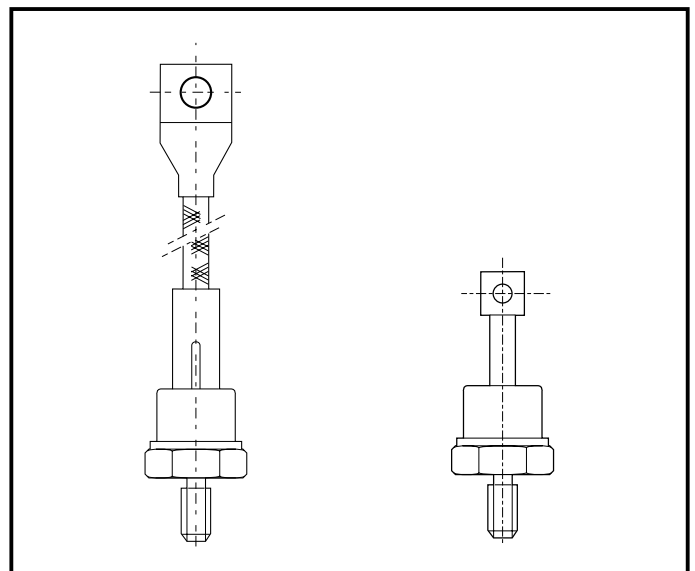
FEATURES

- Thermal Fatigue Free Pressure Contact
- High Surge Capability
- Low Recovery Charge

VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage V_{RRM} V	Conditions
SV15 16F M or K	1600	$V_{RSM} = V_{RRM} + 100V$
SV15 14F M or K	1400	
SV15 12F M or K	1200	
SV15 10F M or K	1000	
SV15 08F M or K	800	
SV15 06F M or K	600	

For 1/2" 20 UNF thread, add suffix K, e.g. SV15 16FK.
 For M12 thread, add suffix M, e.g. SV15 16FM.
 For stud anode add 'R' to type number, e.g. SV15 16FMR.
 For outline DO8C add suffix 'C' to typ number,
 e.g. SV15 16FKC.



Outline type codes: DO8 and DO8C.
See Package Details for further information.

CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{F(AV)}$	Mean forward current	Half wave resistive load, $T_{case} = 65^{\circ}C$	205	A
$I_{F(RMS)}$	RMS value	$T_{case} = 65^{\circ}C$	236	A

SV15..F

SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; with 0% V_{RRM} , $T_j = 150^\circ\text{C}$	3.0	kA
I^2t	I^2t for fusing		45×10^3	A^2s
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; with 50% V_{RRM} , $T_j = 150^\circ\text{C}$	-	kA
I^2t	I^2t for fusing		-	A^2s

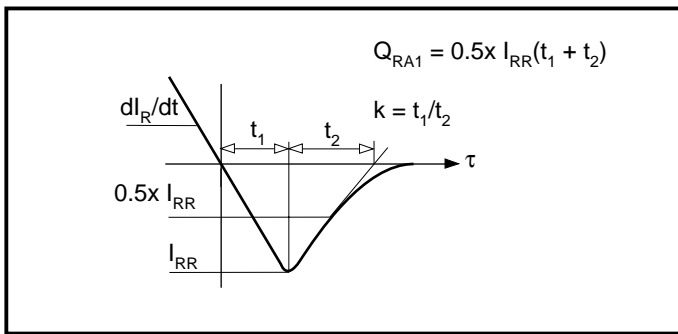
THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.23	$^\circ\text{C}/\text{W}$
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 15Nm with mounting compound	-	0.02	$^\circ\text{C}/\text{W}$
T_{vj}	Virtual junction temperature	On-state (conducting)	-	150	$^\circ\text{C}$
T_{stg}	Storage temperature range		-55	200	$^\circ\text{C}$
-	Mounting torque		12.0	15.0	Nm

CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
V_{FM}	Forward voltage	At 450A peak, $T_{case} = 25^\circ\text{C}$	-	1.6	V
I_{RRM}	Peak reverse current	At V_{RRM} , $T_{case} = 150^\circ\text{C}$	-	20	mA
t_{rr}	Reverse recovery time	$I_F = 450\text{A}$, $di_{RR}/dt = 10\text{A}/\mu\text{s}$ $T_{case} = 125^\circ\text{C}$, $V_R = 100\text{V}$	-	3.2	μs
Q_{RA1}	Recovered charge (50% chord)		-	35	μC
I_{RM}	Reverse recovery current		-	21	A
K	Soft factor		-	-	-
V_{TO}	Threshold voltage	At $T_{vj} = 150^\circ\text{C}$	-	1.0	V
r_T	Slope resistance	At $T_{vj} = 150^\circ\text{C}$	-	1.33	$\text{m}\Omega$
V_{FRM}	Forward recovery voltage	$di/dt = 1000\text{A}/\mu\text{s}$, $T_j = 125^\circ\text{C}$	-	-	V

DEFINITION OF K FACTOR AND Q_{RA1}



CURVES

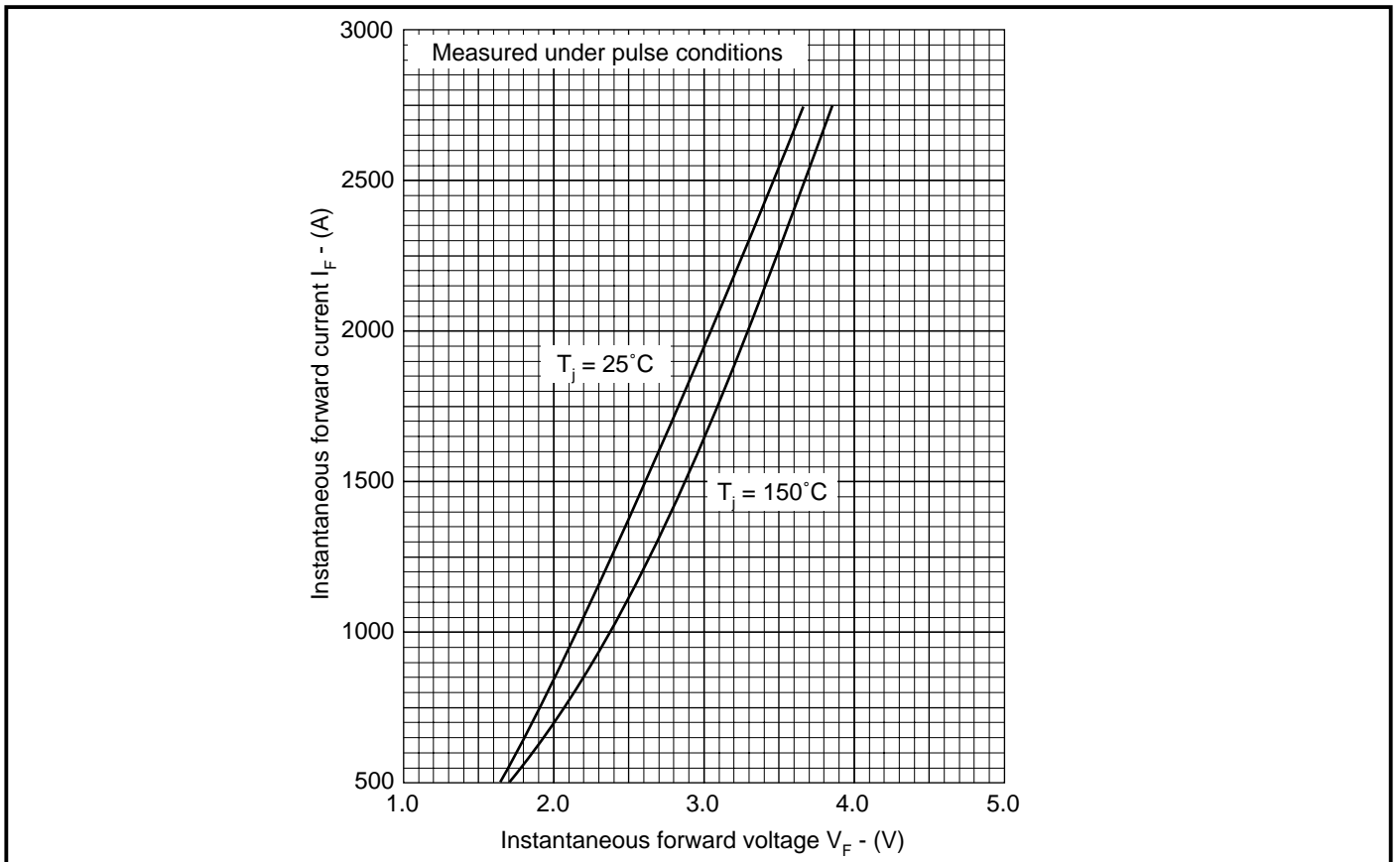


Fig.1 Maximum (limit) forward characteristics

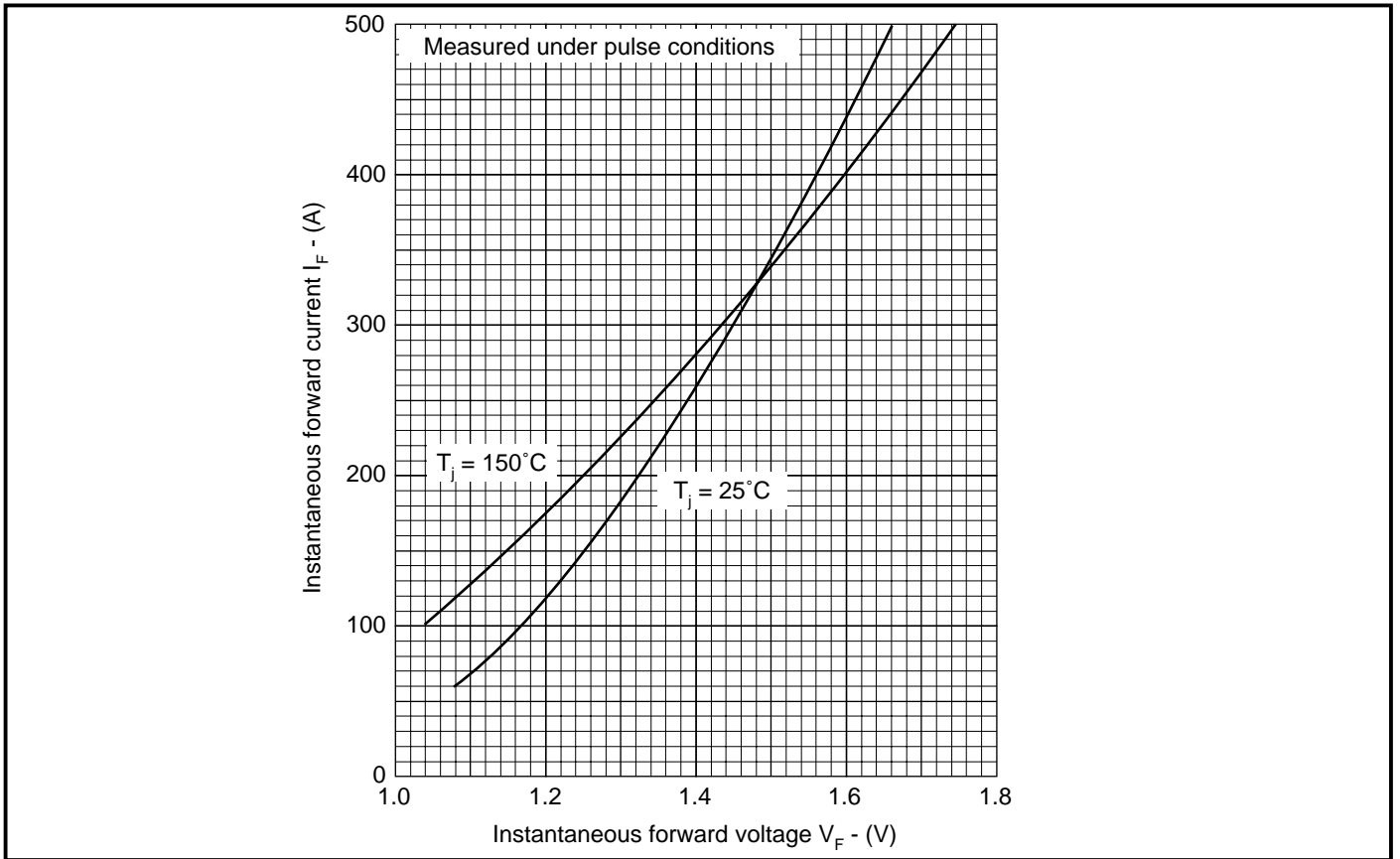


Fig.2 Maximum (limit) forward characteristics

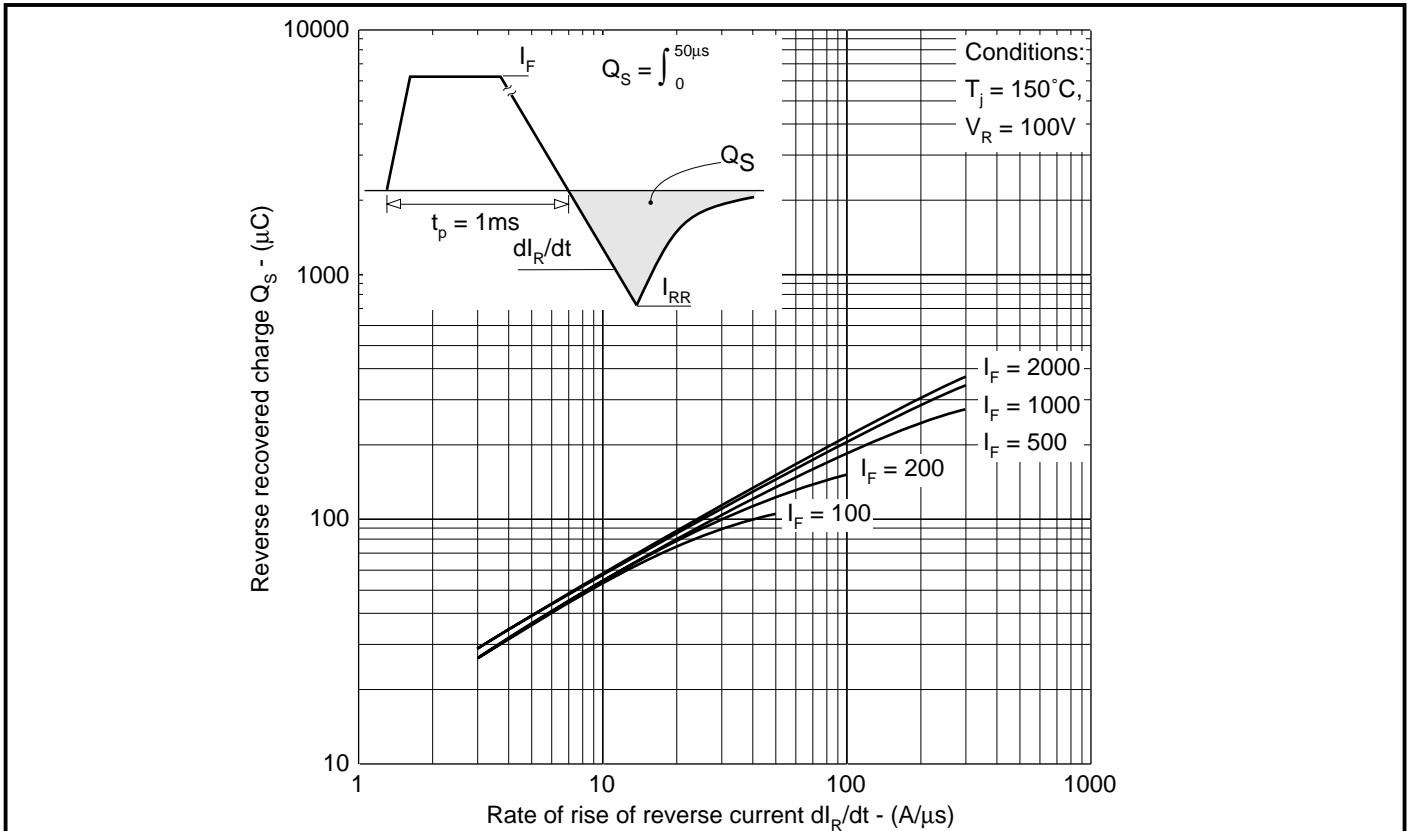


Fig.3 Recovered charge

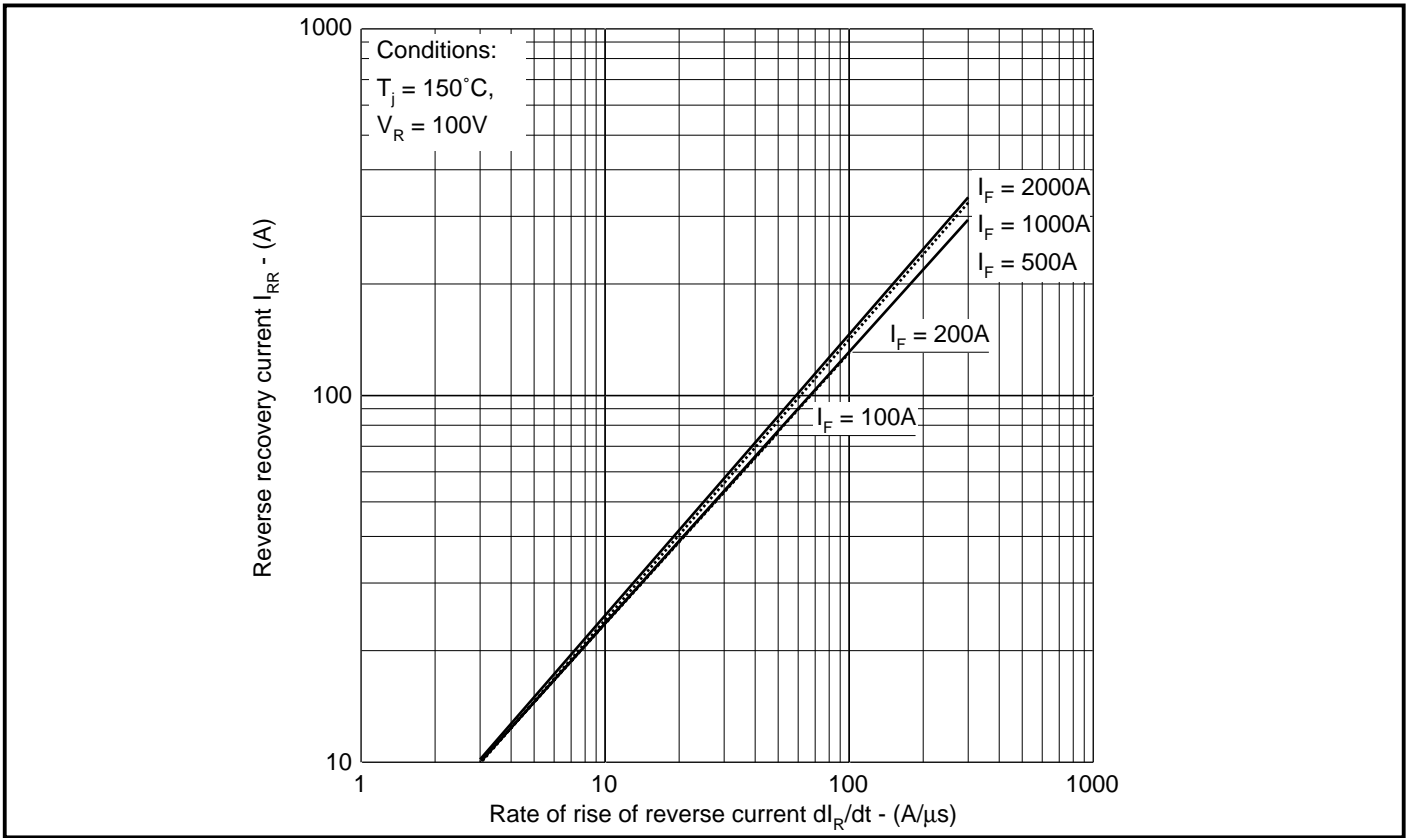


Fig.4 Typical reverse recovery current vs rate of rise of reverse current

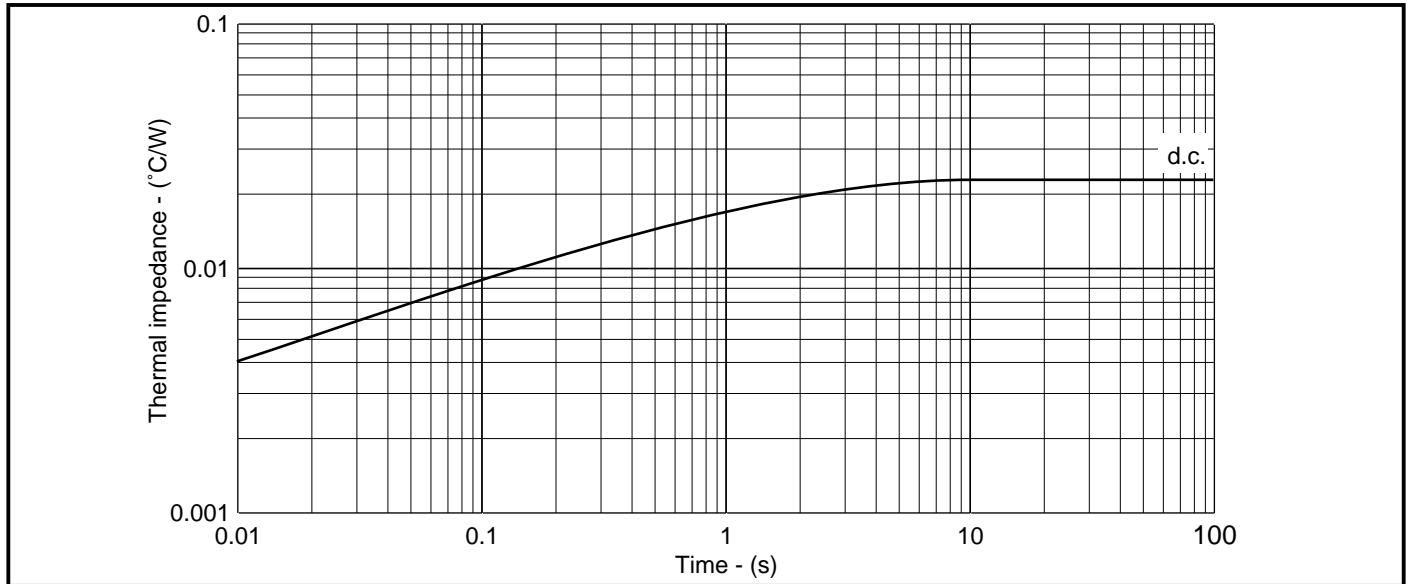
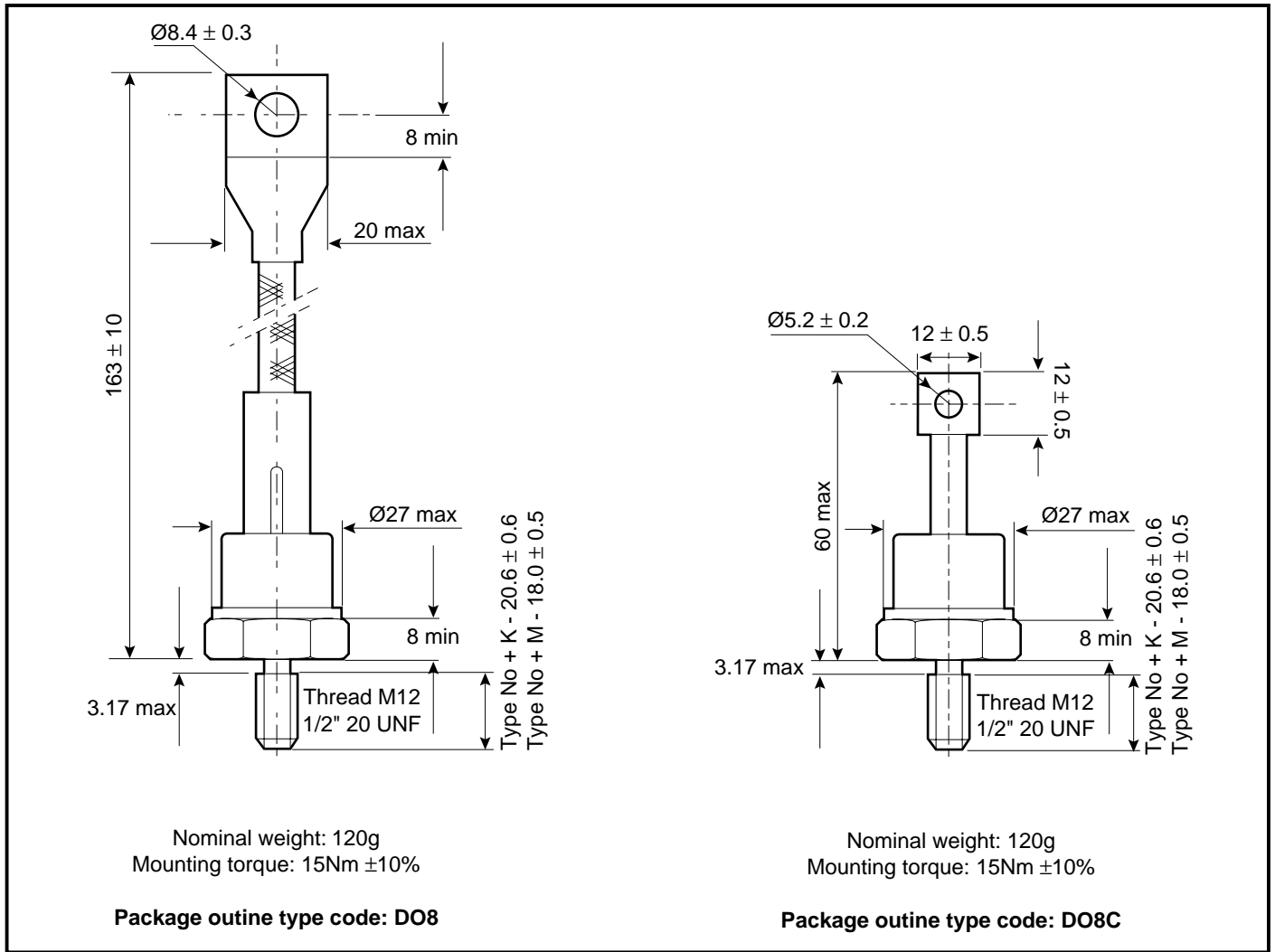


Fig.5 Maximum (limit) transient thermal impedance - junction to case - ($^\circ\text{C/W}$)

SV15..F

PACKAGE DETAILS

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



ASSOCIATED PUBLICATIONS

Title	Application Note
	Number
Calculating the junction temperature or power semiconductors	AN4506
Thyristor and diode measurement with a multi-meter	AN4853
Use of V_{TO} , r_T on-state characteristic	AN5001

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

HEATSINKS

Power Assembly has its own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance of our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or the factory.



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Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

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